

Product/process change notification

PCN N° 2021-014-A1 update

- Updated information marked in BLUE TYPE
- Original PCN N° 2021-014-A dated 2022-03-09

Dear customer,

The previous PCN 2021-014-A has been updated.

Change of assembly production / final test from AMKOR Technology Philippines Inc. Site P3/P4, Philippines / Infineon Technologies Asia Pacific Pte. Ltd., Singapore to UTAC Thai Limited (UTL), Thailand for EiceDRIVER™ products in WSON-8 package inclusive of information on change of BOM

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2022-12-16
- Infineon aligns with the widely recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies AG to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress.

We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

Infineon Technologies AG

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Product/process change notification

PCN N° 2021-014-A1 update

► **Products affected**Please refer to attached affected product list "PCN_2021-014-A1_[customer-no].pdf"

▶ Detailed change information

Subject	Change of Assembly Production and Final test location. Inclusive of BOM (Bill of Material) change information.				
Reason	Ensure continuity of supply.				
Description	Old	New			
Assembly Location	 AMKOR Technology Philippines Inc. Site P3/P4 	■ UTAC Thai Limited (UTL), Thailand			
Test Location	 Infineon Technologies Asia Pacific Pte. Ltd., Singapore 	■ UTAC Thai Limited (UTL), Thailand			
Tester Platform	■ Teradyne µFlex	■ Teradyne ETS88			
Others		■ New bonding-scenario			
Die Attach Material	■ CRM 1085 A	■ Ablebond 8600			
Molding Compounds	■ EME G631 BQF	■ EME G700 LTD			
Bond Wire Diameter	■ 30um Cu	■ 25um Cu			

▶ **Product identification** Internal traceability ensured via datecode and lotcode.

▶ Impact of change NO change on product performance.

► Attachments

1_cip21014_A affected product list
2_cip21014_A Reliability report

 ▶ Time schedule
 2021-014-A
 2021-014-A1

 ■ Final qualification report
 available
 available

 ■ First samples available
 available
 on request

2022-11-30

If you have any questions, please do not hesitate to contact your local sales office.

Intended start of delivery

2022-04-15

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Affected products sold to FUTURE ELECTRONICS INC. (4048203)

Sales name	SP number	OPN	Package	Customer part number
2EDN7524G	SP001391108	2EDN7524GXTMA1	PG-WSON-8	2EDN7524GXTMA1

RESTRICTED

Qualification Test Report



Date: 2022-02-18
Change of Assembly Production / Final test from AMKOR Technology Philippines Inc. Site P3/P4, Philippines / Infineon Technologies Asia Pacific Pte. Ltd., Singapore to UTAC Thai Limited (UTL), Thailand for EiceDRIVER ** products in WSON-8 package

Reason for choosing the following test vehicles (sales name, package name): 2EDN7524G, PG-WSON-8 Package to be qualified

Scope of qualification: new package release for the following product family: 2EDN7224G, 2EDN7523G, 2EDN7524G, 2EDN8523G, 2EDN8524G

Assessment of Q-Results:

Stress test	Abbreviation	Test conditions	Readout	2EDN7524G PG-WSON-8	2EDN7524G PG-WSON-8	2EDN7524G PG-WSON-8
				fails / stressed	fails / stressed	fails / stressed
MSL Preconditioning JESD22-A113	PC	MSL 1 3 x reflow soldering, 260°C	0 h	0 / 231	0 / 231	0 / 154
High Temperature Storage Life JESD22-A103	HTSL	Ta = 150 °C	1000 h	0 / 77	0 / 77	0/77
Humidity Bias (Highly Accelerated Temperature and Humidity Stress) JESD22-A110	HAST	with preconditioning Ta = 130 °C, RH = 85%, Vcc max	96 h	0 / 77	0/77	-
Unbiased Temperature/Humidity JESD22-A118	uHAST	with preconditioning Ta = 130 °C, RH = 85%,	96 h	0 / 77	0 / 77	0/77
Temperature Cycling JESD22-A104	тс	with preconditioning T min = - 65°C T max = 150°C	500 x	0 / 77	0 / 77	0/77
Electrical Parameter Assessment JESD86	ED	Ta = 25 °C		0 / 30	0 / 30	0/30
Electrostatic Discharge Charged Device Model ANSI/ESDA/JEDEC JS-002	ESD-CDM	Ta = 25 °C		Class C3: > 1000 V	-	-



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Sales name	SP number	OPN	Package
2EDN7224G	SP001622940	2EDN7224GXTMA1	PG-WSON-8
2EDN7524G	SP001391108	2EDN7524GXTMA1	PG-WSON-8
2EDN8524G	SP001490806	2EDN8524GXTMA1	PG-WSON-8